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DESIGN INFORMATION

MIN. TRACK WIDTH: 10 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL  
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:  
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC DRILL FILES  
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER  
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENERP  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE:  
MHR047

DESIGNED FOR:  
Public Release

FILE NAME:  
OPT3006EUM\_PCB.PcbDoc

ENGINEER:  
James Becker

LAYOUT BY:  
Krypton Solutions - PS

SCALE: 0.72

ALTIM DESIGNER VERSION:  
16.0.5.271